

SRIDB5050R SERIES

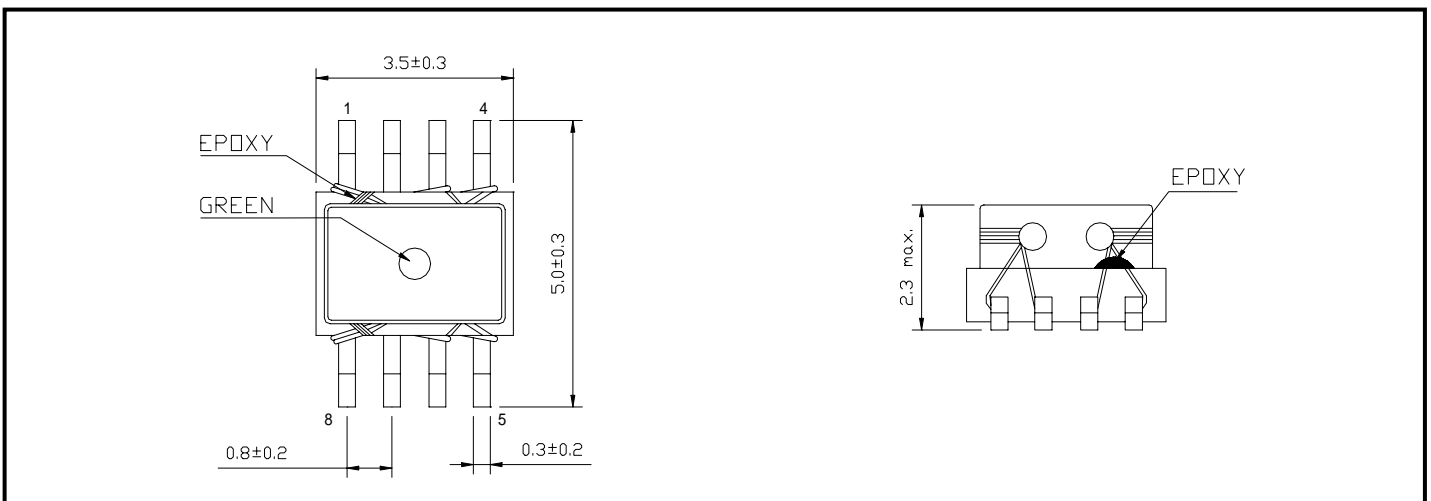


PART NUMBERING SYSTEM

SRIDB	5 0 5 0	-	9 0 0 R	- LF
TYPE	DIMENSIONS		IMPEDANCE	LEAD FREE

SHAPES AND DIMENSIONS

UNIT : mm



SPECIFICATION TABLE

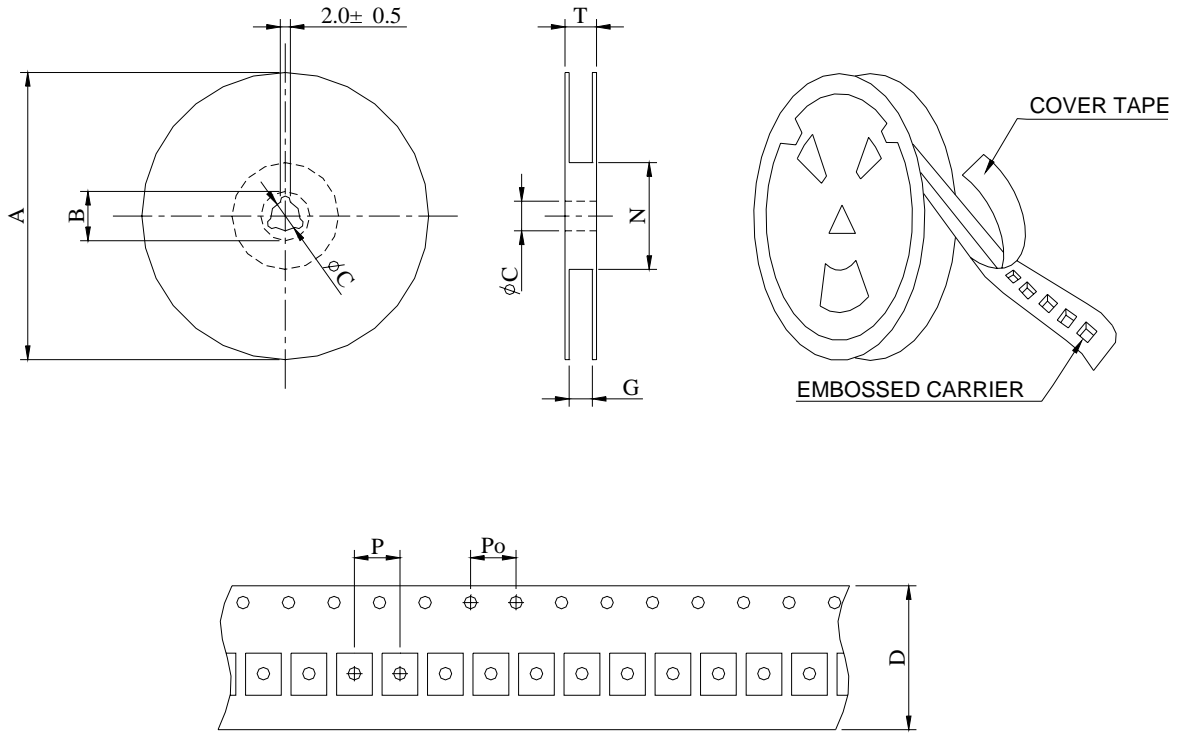
PART NUMBER	RATED CURRENT (mA)	COMMON MODE IMPEDANCE ()		DCR () max.	WITHSTANDING VOLTAGE (Vdc)	INSULATION RESISTANCE () (min)	OPERATING TEMP. ()
		100MHz	300MHz				
SRIDB5050-900R-LF	500	90±25%	250 (TYP.)	0.10	100	100 M	-40~+85
SRIDB5050-201R-LF	500	200±25%	300 (TYP.)	0.12	100	100 M	-40~+85
SRIDB5050-301R-LF	500	300±25%	530 (TYP.)	0.15	100	100 M	-40~+85
SRIDB6560-501R-LF	500	500±25%	900 (TYP.)	0.16	100	100 M	-40~+85

TEST EQUIPMENT : HP-4291A

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PACKAGING SPECIFICATION

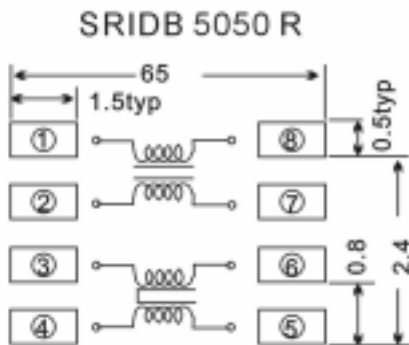


SERIES	STAYLE	Q ' TY (PCS)	DIMENSIONS (m/m)								
			A	B±0.8	C±0.5	D	G ⁺⁰	N ⁰	P	Po	T
SRIDB5050R	12	3000	330	21	13	12	12.4	75	8	4	16.4

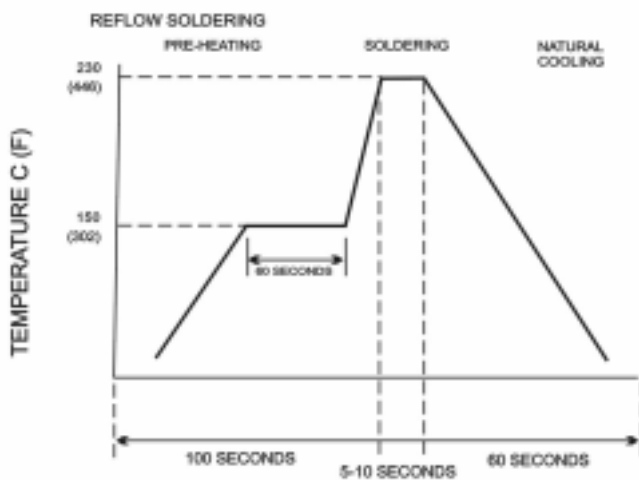
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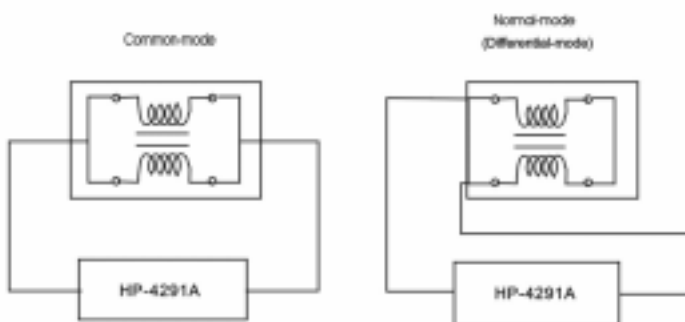
RECOMMENDED PC BOARD PATTERN (unit:mm)



RECOMMENDED REFLOW SOLDERING CONDIDIONS



MEASURING CIRCUIT

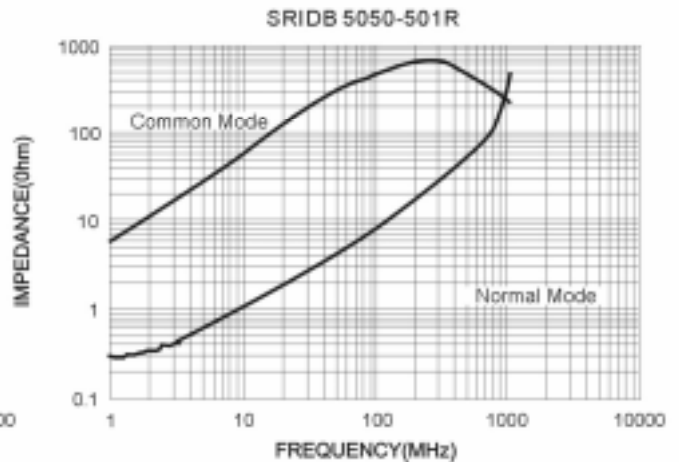
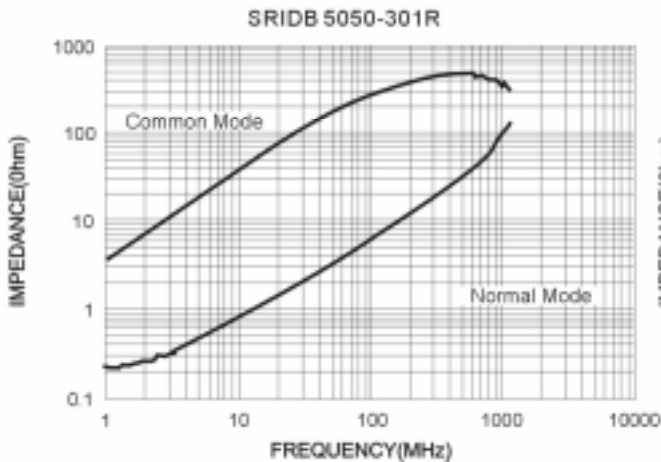
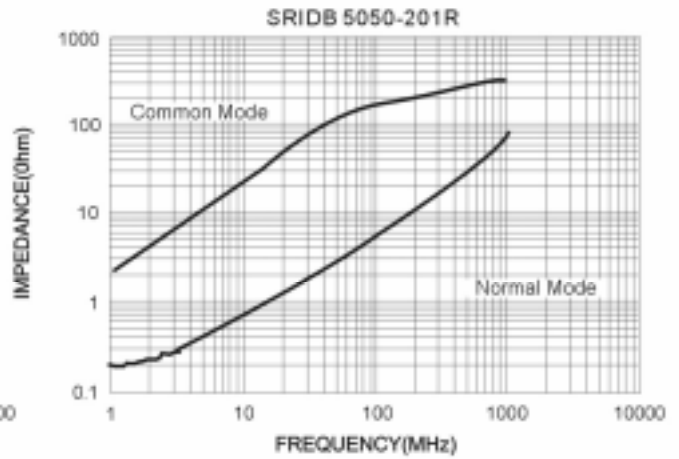
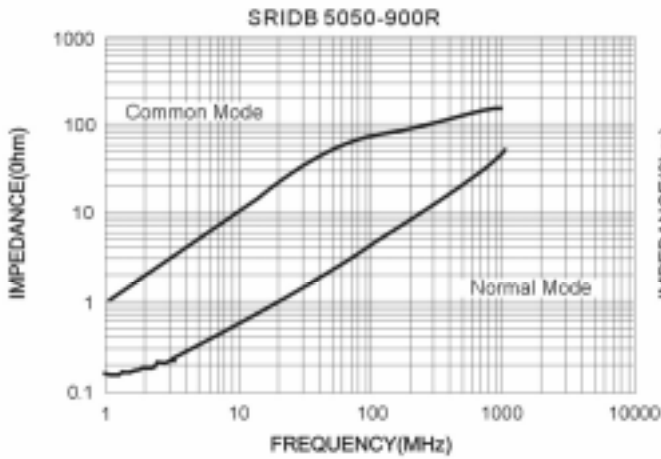


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TYPICAL ELECTRICAL CHARACTERISTICS

SRIDB 5050R SERIES COMMON MODE vs. NORMAL MODE CHARACTERISTICS





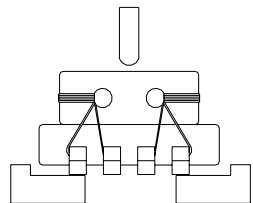


RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
ELECTRICAL PERFORMANCE TEST		
INSERTION LOSS	REFER TO STANDARD ELECTRICAL CHARACTERISTIC LIST	HP-8714C OR EQUIV
IMPEDANCE		HP-4291A OR EQUIV
WITHSTAND VOLTAGE		CH-901 OR EQUIV
TEMPERATURE RISE TEST	40 MAX (t)	<ol style="list-style-type: none"> APPLIED THE ALLOWED DC CURRENT FOR 4 HOURS. TEMPERATURE MEASURE BY DIGITAL SURFACE THERMOMETER.
<u>MECHANICAL PERFORMANCE TEST</u>		
SOLDER HEAT RESISTANCE	<ol style="list-style-type: none"> PRODUCT SHOULD HAVE NO EVIDENCE OF ELECTRICAL AND MICHANICAL DAMAGE. IMPEDANCE SHOULD NOT CHANGE MORE THAN $\pm 10\%$. 	PREHEAT : 150 60SECS SOLDER TEMPERATURE : 260 ± 5 FLUX : ROXIN DIP TIME : 5 ± 2 SECS <div style="text-align: right;"> </div>
VIBRATION TEST (LOW REQUENCY)		<ol style="list-style-type: none"> AMPLITUDE : 1.5mm FREQUENCY : 10-55-10HZ / 1 MIN DIRECTION : X, Y, Z DURATION : 2 HRS/X, Y, Z
SHOCK TEST		INDUCTORS SHOULD BE DROPPED 10 TIMES FROM A HEIGHT OF 1m ONTO 3cm WOODEN BOARD.
SOLDERABILITY TEST	MORE THAN 90% OF TERMINDAL ELECTRODE SHOULD BE COVERED WITH SOLDER.	AFTER FLUXING, INDUCTOR SHALL BE DIPPED IN A MELTED SOLDER BATH AT 230 ± 5 FOR 5 SECONDS. <div style="text-align: right;"> </div>



RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
MECHANICAL PERFORMANCE TEST		
COMPONENT ADHESION (PUSH TEST)	0.8Kg Min	<p>THE DEVICE SHOULD BE REFLOW SOLDERED (232 ± 5 FOR 10 SECONDS) TO A TINNED COPPER SUBSTRATE A DYNOMETER FORCE GAUGE SHOULD BE APPLIED TO THE SIDE OF THE COMPONENT THE DEVICE MUST WITH-ST1.0Kg WITHOUT AILURE OF THE TERMINATION</p>  <p>ATTACHED TO COMPONENT</p>
COMPONENT ADHESION (PULL TEST)	0.75Kg Min	<p>1.INSERT 10cm WIRE INTO THE REMAINING OPEN EYE BEND THE ENDS OF EVEN WIRE LENGTHS UPWARD AND WIND TOGETHER</p> <p>2.TERMINAL SHALL NOT BE REMARKABLY DAMAGED</p> 
FLEXTURE STRENGTH	THE FORCES APPLIED SHOULD NOT DAMAGE THE DIELECTRIC	<p>SOLDER A CHIP ON A TEST SUBSTRATE, BEND THE SUBSTRATE BY 2mm AND RETURN.</p> 
RESISTANCE TO SOLVENT TEST	THERE SHOULD BE NO CASE DEFORMATION, CHANGE IN APPEARANCE OR BITERATION OF MARKING	PRODUCT SHALL WITHSTAND 6 MINTES OF ALCOHOL



RELIABILITY TEST

TEST ITEMS	SPECIFICATIONS	TEST CONDITIONS/TEST METHODS
CLIMATIC TEST		
TEMPERATURE CHARACTERISTIC	1. APPEARANCE NO DAMAGE 2. IMPEDANCE : WITHIN±20% OF INITIAL VALUE	-25 +85
HUMIDITY TEST		1. TEMPERATURE : 60 ±2 2. HUMIDITY : 90-95%RH 3. APPLIED CURRENT : MAX RATED CURREN 4. TIME : 96±2 HOURS 5. MEASURE AT ROOM TEMPERATURE AFTER PLACING FOR 24HRS
LOW TEMPERATURE STORAGE		1. TEMPERATURE : -25 ±2 2. TIME : 96±2 HOURS 3. MEASURE AT ROOM TEMPERATURE AFTER PALCING FOR 24 Hrs
THERMAL SHOCK TEST		1. -40 FOR 5 MINUTES CONTINUE 1 HOUR AND 55 MINUTES +85 FOR 5 MINUTES CONTINUE 1 HOUR AND 55 MINUTE 2. TOTAL 4 CYCLES
HIGH TEMPERATURE STORAGE		1. APPLIED CURRENT : MAX RATED CURRENT 2. TEMPERATURE : 85 ±2 3. TIME : 96±2 HOURS 4. MEASURE AT ROOM TEMPERATURE AFTER PLACING FOR 24HRS
NOTE : PRODUCT ARE TO BE TESTED AFTER 4 HOUR AT ROOM TEMPERATURE		
<u>LIFE TEST</u>		
HIGH TEMPERATURE LOAD LIFE TEST	PRODUCT SHOULD BE NO EVIDENCE OF SHORT OR OPEN CIRCUIT	1. TEMPERATURE : 85±2 2. TIME : 500±12 HOURS 3. LOAD : ALLOWED DC CURRENT
HUMIDITY LOAD LIFE TEST		1. TEMPERATURE : 60±2 2. R.H. : 90-95% 3. TIME : 500±12 HOURS 4. LOAD : ALLOWED DC CURRENT